# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**

[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>HP ProDesk 600 G2 SFF Business PC</th>
</tr>
</thead>
<tbody>
<tr>
<td>Name / Model #2</td>
</tr>
<tr>
<td>Name / Model #3</td>
</tr>
<tr>
<td>Name / Model #4</td>
</tr>
<tr>
<td>Name / Model #5</td>
</tr>
</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Acbel STD</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

Table: Tools Required

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose the screw and remove access panel. (see Figure 1 below)
2. Rotate the driver cage form the hook on slide rail. (see Figure 2 below)
3. Disconnect FIO cables from the MB. (see Figure 3-5 below)
4. Disconnect SATA cables from the MB. (see Figure 6 below)
5. Disconnect other PSU cables from the MB. (see Figure 7-11 below)
6. Remove HDD/ODD from chassis. (see Figure 12-20 below)
7. Remove the heatsink from MB. (see Figure 21-24 below)
8. Separate the fan from CPU heatsink. (see Figure 25-26 below)
9. Remove the CPU from the MB. (see Figure 27-28 below)
10. Remove the Memory card from the MB. (see Figure 29 below)
11. Remove the battery from the MB. (see Figure 30 below)
12. Remove M/B from chassis. (see Figure 31-32 below)
13. Remove front panel from chassis. (see Figure 33 below)
14. Remove FIO/Speaker/LED holder from chassis. (see Figure 34-36 below)
15. Remove PSU cover. (see Figure 37-43 below)
16. Disconnect all the cables and remove the Electrolytic Capacitors. (see Figure 44-47 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 pull the handle and remove access panel

Figure 2 Rotate the driver cage from the hook

Figure 3 Disconnect FIO Audio cables from MB

Figure 4 Disconnect FIO USB3.0 cables from MB

Figure 5 Disconnect FIO USB2.0 cables from MB

Figure 6 Disconnect SATA cables from the MB
Figure 7 Disconnect Speaker cable from the MB
Figure 8 Disconnect ODD/HDD PSU cables from the MB

Figure 9 Disconnect MB PSU cable from the MB
Figure 10 Disconnect other PSU cables from the MB

Figure 11 Disconnect CPU Power cable from the MB
Figure 12 Disconnect HDD Power cable from HDD
Figure 13 Disconnect SATA cable from HDD

Figure 14 Remove the cables from the chassis clip

Figure 15 Press the HDD’s latch on HDD cage

Figure 16 Remove the HDD from HDD cage

Figure 17 Disconnect ODD power cable from ODD

Figure 18 Disconnect SATA cable from ODD
Figure 19 Press the ODD’s latch on ODD cage

Figure 20 Remove the ODD from ODD cage

Figure 21 Rotate the Fan duct 01 and remove it

Figure 22 Press the hook and remove fan duct 02

Figure 23 Disconnect heat sink fan cable from MB

Figure 24 Loosen the screws and remove heat sink
Loose the screws and remove the fan

Separate the fan from CPU heat sink

Rotate the handle and open it up

Remove the CPU from the board

Remove the Memory card from the board

Remove the battery from the system board

PSG instructions for this template are available at EL-MF877-01
Figure 31: Loose the screws of MB from board

Figure 32: Remove MB from chassis

Figure 33: Remove front panel from chassis

Figure 34: Loose the screws of FIO and remove it

Figure 35: Loose the screws of speaker and remove it

Figure 36: Remove the holder of LED power cable from chassis
Figure 37 Remove the screws on the PSU chassis

Figure 38 Press the PSU’s latch on chassis

Figure 39 Remove the Power supply from chassis

Figure 40 Remove screw for top

Figure 41 Remove the screw form the bottom

Figure 42 Remove screw for front
Figure 43 Remove the screw and open case

When removed only PCBA left

Figure 44 Disconnect the cable-wire from product

Figure 45 Loose the screw of PCBA cable

Figure 46 When removed only PCBA left

Figure 47 Show Ele-Cap on PCBA